## AE6705 Lab 2 Code Composer Studio

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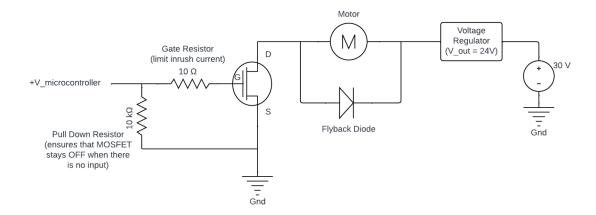
1. (Debugging) In the variables window, right click on the Value property of cm. Change the Number Format to hexadecimal. What is the value shown? Confirm that this value is equal to the decimal value displayed (show your work).

```
cm = 1000 (default decimal) = 0x000003E8 (hex) 
0x000003E8 = 8 \times 16^0 + 14 \times 16^1 + 3 \times 16^2 = 8 + 224 + 768 = 1000
```

2. (Debugging) Now press F8 four more times (or click on the Resume button four more times), letting the program stop at line 36 before each time you press it. Monitor the value of counter in the Expressions window. What is the value of counter after you have pressed F8 four times? After changing the displayed format to binary, how many bits are shown? Why is this number of bits displayed (recall data types)?

In the code, cm is set to counter \* 1000, resuming 4 more times increments the counter by 4. cm = 5000 (default decimal) = 00000000000000000001001110001000b (binary) 32 bits are shown because cm is declared as type int, which has the size 4 bytes or 32 bits

3. (Circuit Design) Design a circuit that uses a solid state (semiconductor) device to switch a DC motor ON or OFF. The circuit should be able to handle high current spikes. The voltage source available is a 30VDC power supply. The motor specifications are given in the "DC motor.pdf" file (use the second motor requiring rated 24VDC supply). Notice the starting current of the motor is a high value. (Hint: Consider using a transistor-based switching circuit such as that shown in Slide 38 of Lecture 2, with appropriate modifications as desired.)



4. (Circuit Design) Find a solid state (semiconductor) switching device on the internet that can be used in the above circuit. Attach the datasheet for this device. Point out to the important details in the datasheet of the device that proves the usability of the device.

Table 1: Motor Specs

Operating Voltage (V)	10.8 to 26.4
Rated Voltage (V)	24.0
No Load Current (mA)	35
Rated Load Current (mA)	159
Starting Current (mA)	815

NTE2980 (N channel MOSFET) can be used as the switching device. The specs pdf is attached to the end of this report.

- Max. drain current:  $I_D = 7.7A$  at room temperature, well above the maximum current the motor might draw when starting up, 815 mA
- Drain-Source Breakdown Voltage:  $V_{DSS} = 60V$ . If the voltage between the drain and the source exceeded this during the OFF state, current will start to flow. This is selected to be well above the operating voltage of the motor to ensure that there would be no current flowing in the OFF state.
- Gate threshold voltage:  $V_{GS(th)} = 1 2V$ . This switch can be turned ON/OFF using our microcontroller.



# NTE2980 Logic Level MOSFET N-Channel, Enhancement Mode High Speed Switch TO251

#### Features:

- Dynamic dv/dt Rating
- Logic Level Gate Drive
- R<sub>DS</sub>(on) Specified at V<sub>GS</sub> = 4V & 5V
- Fast Switching
- TO251 Type Package

#### **Absolute Maximum Ratings:**

Drain Current, I <sub>D</sub>	
Continuous (V <sub>GS</sub> = 5V)	
$T_C = +25^{\circ}C$	7.7A
$T_{C} = +100^{\circ}C$	4.9A
Pulsed (Note 1)	31A
Total Power Dissipation (T <sub>C</sub> = +25°C), P <sub>D</sub>	25W
Derate Above 25°C	0.20W/°C
Total Power Dissipation (PC Board Mount, T <sub>C</sub> = +25°C, Note 2), P <sub>D</sub>	2.5W
Derate Above 25°C	
Gate-Source Voltage, V <sub>GS</sub>	
Single Pulsed Avalanche Energy (Note 3), EAS	
Peak Diode Recovery dv/dt (Note 4), dv/dt	4.5V/ns
Operating Junction Temperature Range, T <sub>J</sub>	55° to +150°C
Storage Temperature Range, T <sub>stg</sub> –	55° to +150°C
Maximum Lead Temperature (During Soldering, 1.6mm from case, 10sec), T <sub>L</sub>	+260°C
Maximum Thermal Resistance:	
Junction-to-Case, R <sub>thJC</sub>	5.0°C/W
Junction-to-Ambient (PCB Mount, Note 2), R <sub>thJA</sub>	50°C/W
Junction-to-Ambient, R <sub>thJA</sub>	110°C/W
Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature.	
Note 2. When mounted on a 1" square PCB (FR-4 or G-10 material).	
Note 3. L = $924\mu H$ , $V_{DD} = 25V$ , $R_G = 25\Omega$ , Starting $T_J = +25^{\circ}C$ , $I_{AS} = 7.7A$ .	
Note 4. $I_{SD} \le 10A$ , $di/dt \le 90A/\mu s$ , $V_{DD} \le V_{(BR)DSS}$ , $T_{J} \le +150^{\circ}C$ .	
11010 1. 150 - 1011, dilat = 0011/40, 100 = 1 (BH)025, 13 = 1100 0.	

### **Electrical Characteristics:** $(T_J = +25^{\circ}C \text{ unless otherwise specified})$

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit		
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	$V_{GS} = 0V, I_D = 250\mu A$	60	_	_	V		
Breakdown Voltage Temperature Coefficient	$\Delta V_{(BR)DSS}/$ $\Delta T_J$	Reference to +25°C, I <sub>D</sub> = 1mA	_	0.073	-	V/°C		
Static Drain-Source ON Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 5V, I <sub>D</sub> = 4.6A, Note 5	_	-	0.20	Ω		
		V <sub>GS</sub> = 4V, I <sub>D</sub> = 3.9A, Note 4	_	-	0.28	Ω		
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	1.0	_	2.0	V		
Forward Transconductance	9fs	V <sub>DS</sub> = 25V, I <sub>D</sub> = 4.6A, Note 5	3.4	_	_	mhos		
Drain-to-Source Leakage Current	I <sub>DSS</sub>	$V_{DS} = 60V, V_{GS} = 0$	_	-	25	μΑ		
		$V_{DS} = 48V, V_{GS} = 0V, T_{C} = +125^{\circ}C$	_	_	250	μΑ		
Gate-Source Leakage Forward	I <sub>GSS</sub>	V <sub>GS</sub> = 10V	_	_	100	nA		
Gate-Source Leakage Reverse	I <sub>GSS</sub>	V <sub>GS</sub> = -10V	_	_	-100	nA		
Total Gate Charge	$Q_g$	$V_{GS} = 5V$ , $I_D = 10A$ , $V_{DS} = 48V$ , Note 5	_	_	8.4	nC		
Gate-Source Charge	$Q_{gs}$			_	3.5	nC		
Gate-Drain ("Miller") Charge	Q <sub>gd</sub>			-	6.0	nC		
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{DD}$ = 30V, $I_{D}$ = 10A, $R_{G}$ = 12 $\Omega$ , $R_{D}$ = 2.8 $\Omega$ , Note 5		9.3	_	ns		
Rise Time	t <sub>r</sub>			110	_	ns		
Turn-Off Delay Time	t <sub>d(off)</sub>			17	_	ns		
Fall Time	t <sub>f</sub>			26	_	ns		
Internal Drain Inductance	L <sub>D</sub>	Between lead, 6mm (0.25") from package and center of die contact		4.5	_	nΗ		
Internal Source Inductance	L <sub>S</sub>			7.5	_	nΗ		
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 25V, f = 1MHz	_	400	_	pF		
Output Capacitance	C <sub>oss</sub>			170	_	pF		
Reverse Transfer Capacitance	C <sub>rss</sub>			42	_	pF		
Source-Drain Diode Ratings and	Characterist	ics		•				
Continuous Source Current	I <sub>S</sub>	(Body Diode)	_	_	7.7	Α		
Pulse Source Current	I <sub>SM</sub>	(Body Diode) Note 1	_	-	31	Α		
Diode Forward Voltage	$V_{SD}$	$T_J = +25^{\circ}C$ , $I_S = 7.7A$ , $V_{GS} = 0V$ , Note 5	-	-	1.6	V		
Reverse Recovery Time	t <sub>rr</sub>	$T_J = +25^{\circ}C$ , $I_F = 10A$ , $di/dt = 100A/\mu s$ , Note 5		65	130	ns		
Reverse Recovery Charge	Q <sub>rr</sub>			0.33	0.65	μС		
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is neglegible (turn-on is dominated by $L_S + L_D$ )						

Note 1. Repetitive Rating: Pulse width limited by maximum junction temperature. Note 5. Pulse Test: Pulse Width  $\leq 300 \mu s$ , Duty Cycle  $\leq 2\%$ .